

## AMENDMENT

### **Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

### **Listing of claims:**

WHAT IS CLAIMED IS:

1. (Previously Presented) A plasma processing apparatus comprising:
  - a chamber defining at least one opening and constructed for retaining a generated plasma;
  - a dielectric member positioned to sealingly cover the at least one opening;
  - at least one wave guide provided exteriorly of the chamber such that one end side thereof opposes the dielectric member, wherein the at least one wave guide defines a homogeneous internal volume;
  - an electromagnetic wave source operatively coupled to the other end side of the at least one wave guide;
  - a plurality of holes defined by a side of the at least one wave guide that is in opposition to the dielectric member; and
  - hole area adjusting means including a reciprocatable plate portion provided in at least one of the plurality of holes to adjust the opening area of the hole and thereby modulate the density of plasma generated in said chamber during operation thereof.
2. (Original) A plasma processing apparatus according to claim 1, wherein the hole having the hole area adjusting means has a larger hole area than the areas of the other holes.

3. (Original) A plasma processing apparatus according to claim 2, wherein the hole having the largest hole area is located on the terminal end side of the wave guide.
4. (Original) A plasma processing apparatus according to claim 1, wherein the wave guide includes a plurality of wave guides.
5. (Original) A plasma processing apparatus according to claim 1, wherein at least one of the holes is located near the periphery of the dielectric member.
6. (Previously Presented) A plasma processing apparatus according to claim 1, wherein the wave guide has a rectangular cross-sectional shape, the hole has four sides of a rectangular shape, the dielectric member has four sides of a rectangular shape, and wherein the long sides of the hole are parallel to one side of the dielectric member close thereto.
7. (Original) A plasma processing apparatus according to claim 1, wherein the hole area of the hole on the side wall surface side of the chamber is made the largest, and wherein the hole is provided with the hole area adjusting means.
8. (Original) A plasma processing apparatus according to claim 1, wherein the hole area adjusting means is provided with a metal plate-like portion so as to adjust the opening area of the hole by reciprocating the plate-like portion.
9. (Canceled)

10. (Canceled)

11. (Canceled)

12. (Canceled)

13. (Canceled)